Octal Bus Transceivers/Registers with Multiplexed 3-state outputs

HITACHI

Description

Six control inputs enable this device to be used as a latched transceiver, unlatched transceiver or a combination of both. As a latched transceiver, data from one bus is stored for later retrieval by the other bus. Alternately real time bus data (unlatched) may be directly transferred from one bus to another.

Circuit operation is determined by the Control \overline{G} , Direction, Clock AB, Clock BA, Select AB, Select BA control inputs. The enable input, Contorl \overline{G} , controls whether any bus outputs are enabled. The direction control Direction (DIR), determines which bus is enabled, and hence the direction data flows: The Select AB, Select BA inputs cotrol whether the latched data (stored in D type flip-flops), or the bus data (from other bus input pins) is transferred. Each set of flip-flops has its own clock Clock AB and Clock BA, for storing data. Data is latched on the rising edge of the clock.

Features

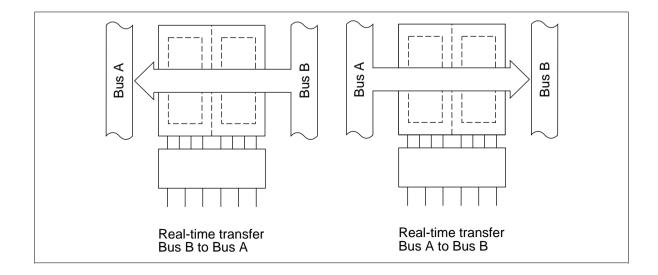
- High Speed Operation: t_{pd} (Bus to Bus) = 14 ns typ ($C_L = 50 \text{ pF}$)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

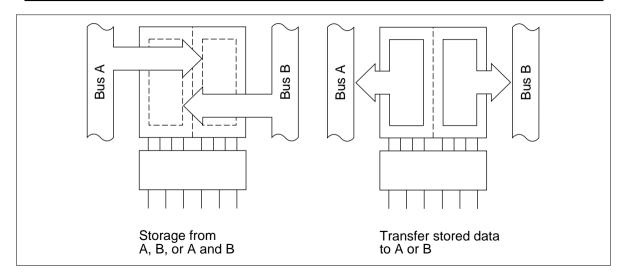


Function Table

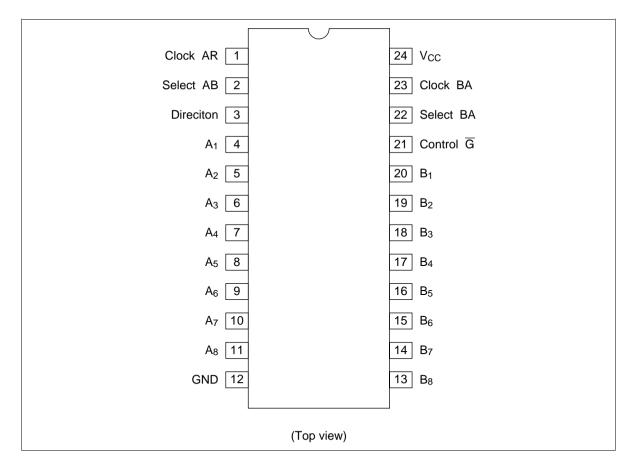
Inputs

Control		Cloc	:k	Sele	ct	Data I/O	Data I/O	Operation or Function				
G	Direction	BA	AB	AB	BA	A1 thru A8	B1 thru B8	HD74HC646	HD74HC648			
Н	Х	Х	Х	Х	Х	Z (Input)	Z (Input)	Isolation	Isolation			
Н	Х	\int		Н	Н	Z (Input)	Z (Input)	Store A & B data	Store $\overline{A} \& \overline{B}$ data			
L	L	Х	Х	Х	L	Output	Z (Input)	B real-time data to A bus	B real-time data to A bus			
L	L	Η	Η	Х	Η	Output	Z (Input)	B stored data to A bus	\overline{B} stored data to A bus			
L	L	L	L	Х	Н	Output	Z (Input)	B stored data to A bus	\overline{B} stored data to A bus			
L	Н	Х	Х	L	Х	Z (Input)	Output	A real-time data to B bus	\overline{A} real-time data to B bus			
L	Н	Η	Η	Η	Х	Z (Input)	Output	A stored data to B bus	Ā stored data to B bus			
L	Н	L	L	Η	Х	Z (Input)	Output	A stored data to B bus	Ā stored data to B bus			





Pin Arrangement

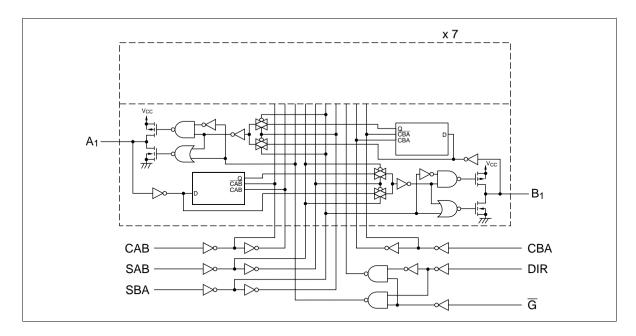


Absolute Maximum Ratings

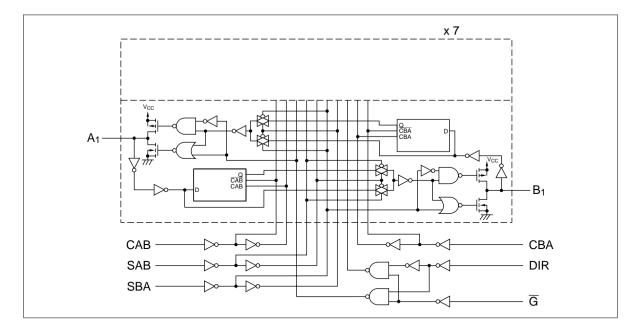
Item	Symbol	Rating	Unit
Supply voltage range	V _{cc}	-0.5 to +7.0	V
Input voltage	V _{IN}	-0.5 to V _{cc} + 0.5	V
Output voltage	V _{OUT}	-0.5 to V _{cc} + 0.5	V
Output current	I _{OUT}	±35	mA
DC current drain per $\rm V_{\rm cc}$, GND	I _{cc} , I _{gnd}	±75	mA
DC input diode current	I _{IK}	±20	mA
DC output diode current	Ι _{οκ}	±20	mA
Power Dissipation per package	P _T	500	mW
Storage temperature	Tstg	-65 to +150	°C

Logic Diagram

HD74HC646



HD74HC648



DC Characteristics

			Ta =	: 25°C	;	Ta = - +85°C	–40 to C			
ltem	Symbol	V_{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	าร
Input voltage	V _{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	—	—	3.15	—	_		
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0		_	0.5	_	0.5	V		
		4.5	—	—	1.35	—	1.35	_		
		6.0		—	1.8	_	1.8			
Output voltage	$V_{\rm OH}$	2.0	1.9	2.0	_	1.9	_	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20 \ \mu A$
		4.5	4.4	4.5	—	4.4	—	_		
		6.0	5.9	6.0	—	5.9	_	_		
		4.5	4.18	_	_	4.13	_	_		I _{он} = —6 mА
		6.0	5.68	_	_	5.63	—			I _{он} = -7.8 mА
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL}$	I _{oL} = 20 μA
		4.5	—	0.0	0.1	—	0.1			
		6.0	_	0.0	0.1	—	0.1			
		4.5	_	_	0.26	—	0.33	_		I _{oL} = 6 mA
		6.0	—	—	0.26	—	0.33			I _{oL} = 7.8 mA
Off-state output current	I _{oz}	6.0	—	—	±0.5	—	±5.0	μA	$Vin = V_{IH} \text{ or } V_{IL},$ Vout = V _{CC} or C	
Input current	lin	6.0		_	±0.1	_	±1.0	μΑ	$Vin = V_{CC} \text{ or } GN$	ND
Quiescent supply current	I _{cc}	6.0	—	—	4.0	—	40	μΑ	Vin = V _{cc} or GN	ND, lout = 0 μ A

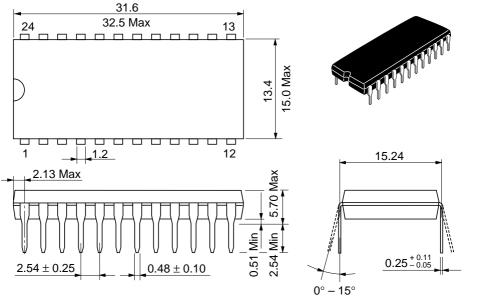
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

			Ta = 25°C			Ta = - +85°0	–40 to C		
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	f_{max}	2.0	_	_	5		4	ns	Clock AB to B or
frequency		4.5	_	—	27	—	21	_	Clock BA to A
		6.0	—	—	32	—	25	_	
Propagation delay	t _{PLH}	2.0	_		170	_	215	ns	A or B input to B or A output
time	t _{PHL}	4.5	_	14	34	—	43	_	(HD74HC646 only)
		6.0	_	_	29	—	37	-	
	t _{PLH}	2.0	_	_	150	_	190	ns	A or B input to B or A output
	t _{PHL}	4.5	_	14	30	_	38	_	(HD74HC648 only)
		6.0		_	26		33	-	
	t _{PLH}	2.0	_	_	220	_	275	ns	Clock BA or Clock AB input to
	t _{PHL}	4.5	_	18	44	—	55	_	A or B output
		6.0	_	_	37	—	47	_	
	t _{PLH}	2.0	_	_	170		215	ns	Select BA or Select AB input to
	t _{PHL}	4.5	_	15	34	—	43	_	A or B output, with A or B high
		6.0	_	_	29	—	37	_	
	t _{PLH}	2.0	_	—	170	_	215	ns	Select BA or Select AB input to
	t _{PHL}	4.5	_	16	34	_	43	-	A or B output, with A or B low
		6.0	_	_	29	—	37	_	
Output enable	t _{zH}	2.0	_	_	150		190	ns	Control \overline{G} input or Direction to
time	t _{zL}	4.5	_	17	30	_	38	-	A or B output
		6.0	_	_	26	_	33	_	
Output disable	t _{LZ}	2.0	_	_	150	_	190	ns	Control \overline{G} input to A or B
time	t _{HZ}	4.5		20	30	_	38	-	output
		6.0	_	_	26	_	33	_	
Setup time	t _{su}	2.0	100	_	_	125	_	ns	
		4.5	20	3	_	25	_	-	
		6.0	17	_	_	21	_	-	
Hold time	t _h	2.0	5	_	_	5	_	ns	
		4.5	5	0	_	5	_	-	
		6.0	5	_	_	5	_	-	

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$) (cont)

			Ta = 25°C		Ta = ∙ +85°0	–40 to C			
ltem	Symbol	V_{cc} (V)	Min	Тур	Мах	Min	Max	Unit	Test Conditions
Pulse width	t _w	2.0	80	_	_	100	_	ns	
		4.5	16	5		20	—	_	
		6.0	14	_		17	_	_	
Output rise/fall	t _{TLH}	2.0			60	—	75	ns	
time	t_{THL}	4.5		4	12	—	15	_	
		6.0		_	10	—	13	_	
Input capacitance	Cin		_	5	10	—	10	pF	

Unit: mm



Hi	itachi Code	DP-24
JE	EDEC	Conforms
EI	AJ	Conforms
W	eight (reference value)	3.1 g

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